

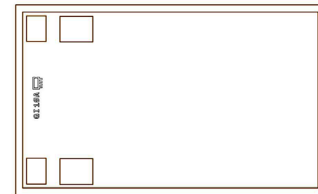
Microwave Gain Equalizer Die

EQY-D-SERIES

50Ω DC to 6 GHz

The Big Deal

- Excellent Return Loss, 20dB typ.
- Wide bandwidth, DC - 6 GHz
- Excellent power handling 31 dBm



Product Overview

EQY Series Dice of absorptive Gain Equalizers are fabricated using highly repetitive GaAs IPD* MMIC process incorporating resistors, capacitors and inductors having negative insertion loss slope. EQYs are available with nominal attenuation slope of 1,2,3,4,5,6,8 & 10 dB.

Key Features

Feature	Advantages
Negative Insertion Loss Slope vs. Frequency	Useful for compensating negative gain slope of amplifiers, receivers, transmitters to achieve flat gain versus frequency.
Wide range of values 1,2,3,4,5,6,8 & 10 dB	Enables circuit designer to change nominal insertion loss values without mother-board redesign making the EQY series ideal for select at test application.
Wideband operation, DC to 6 GHz	Supports a wide array of applications including wireless cellular, microwave communications, satellite, defense and aerospace, medical broadband and optic applications.
Excellent Power Handling Capability 31/32 dBm	Enables its use at the output of a variety of amplifiers
Unpackaged Die	Enables the user to integrate the gain equalizer directly into hybrids

*GaAs IPD (Gallium Arsenide Integrated Passive Device)

Microwave Gain Equalizer Die

EQY-10-63-D+

50Ω 10dB DC to 6 GHz

Product Features

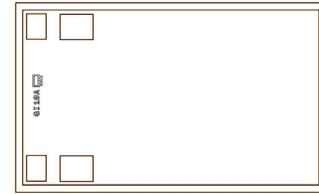
- 10.2 dB Slope
- Excellent power handling 31 dBm
- Wide Bandwidth, DC-6 GHz
- Excellent Return Loss, 20 dB typ.

Typical Applications

- Cellular
- PCS
- Communications
- Radar
- Defense

General Description

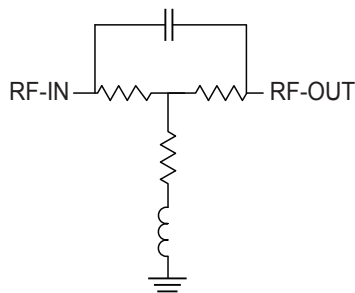
EQY-10-63-D+ is an absorptive Gain Equalizer Die fabricated using highly repetitive GaAs IPD MMIC process incorporating resistors, capacitors and inductors having negative insertion loss slope. EQY-10-63-D+ has a nominal attenuation slope of 10.2 dB.



+RoHS Compliant
The +Suffix identifies RoHS Compliance. See our web site for RoHS Compliance methodologies and qualifications

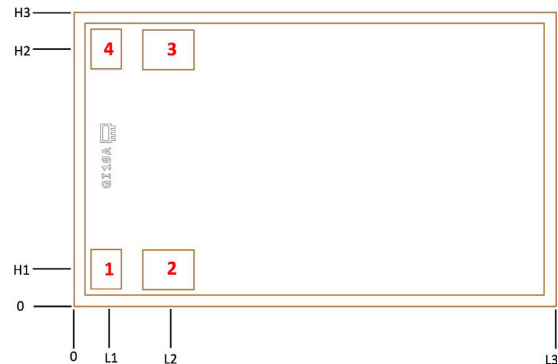
Ordering Information: Refer to Last Page

Simplified Schematic and Pad description



Pad Number	Function	Description
2	RF-IN	RF-Input pad
3	RF-OUT	RF-Output pad
1,4 & Bottom of Die	GND	Ground

Bonding Pad Position



Dimensions in μm , Typical

L1	L2	L3	H1	H2	H3	Thickness	Die Size	Bond Pad #1, #4	Bond Pad #2, #3
79	224	1150	86.5	613.5	700	100	1150x700	67 X 92	117 X 92

Electrical Specifications¹ at 25°C, 50Ω, unless otherwise noted.

Parameter	Condition (GHz)	Min.	Typ.	Max.	Units
Frequency Range		DC		6	GHz
Insertion Loss	0.01		11.2		dB
	1		10.0		
	2		7.5		
	3		4.9		
	4		2.9		
	5		1.7		
VSWR	6		1.0		:1
	0.01 -1		1.06		
	1 - 2		1.03		
	2 - 3		1.05		
	3 - 4		1.05		
	4 - 5		1.04		
	5 - 6		1.12		

1. Measured on Mini-Circuits Characterization Test Board. Die is packaged in 2x2mm, 8-lead MCLP and soldered on testboard TB-1041-10-63+. See Characterization Test Circuit (Fig. 1)

Absolute Maximum Ratings²

Operating Case Temperature	-40°C to 85°C
RF Input Power	31 dBm

2. Permanent damage may occur if any of these limits are exceeded.

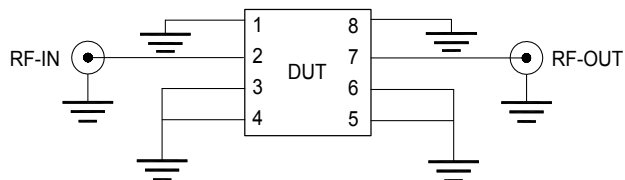
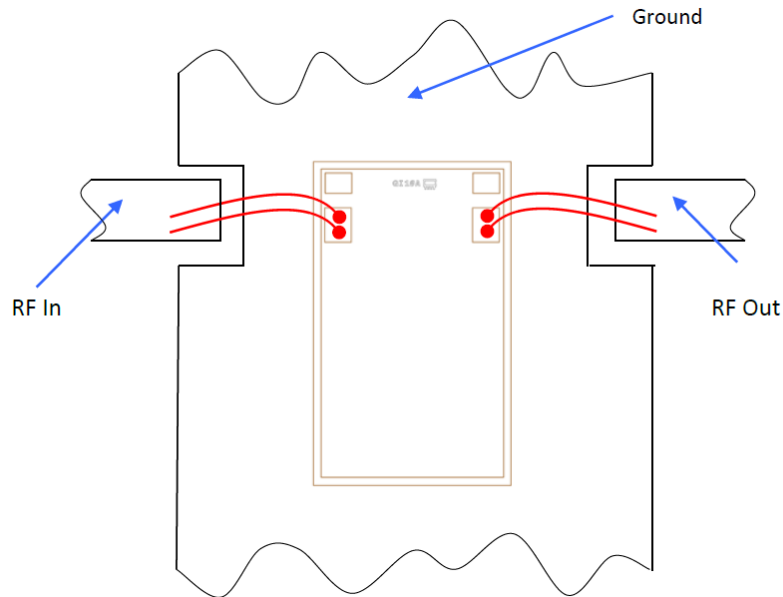
Characterization Test Circuit

Fig 1. Block Diagram of Test Circuit used for characterization. Die is packaged in 2x2mm, 8-lead MCLP and soldered on testboard TB-1041-10-63+
Conditions: Attenuation & Return Loss Pin=0 dBm

Assembly Diagram



Assembly and Handling Procedure

- 1. Storage**
Dice should be stored in a dry nitrogen purged desiccators or equivalent.
- 2. ESD**
MMIC GaAs Gain equalizer dice are susceptible to electrostatic and mechanical damage. Die are supplied in antistatic protected material, which should be opened in clean room conditions at an appropriately grounded anti-static workstation. Devices need careful handling using correctly designed collets, vacuum pickup tips or sharp antistatic tweezers to deter ESD damage to dice.
- 3. Die Attach**
The die mounting surface must be clean and flat. Using conductive silver filled epoxy, recommended epoxies are DieMat DM6030HK-PT/H579 or Ablestik 84-1LMISR4. Apply sufficient epoxy to meet required epoxy bond line thickness, epoxy fillet height and epoxy coverage around total die periphery. Parts shall be cured in a nitrogen filled atmosphere per manufacturer's cure condition. It is recommended to use antistatic die pick up tools only.
- 4. Wire Bonding**
Bond pad openings in the surface passivation above the bond pads are provided to allow wire bonding to the dice gold bond pads. Thermosonic bonding is used with minimized ultrasonic content. Bond force, time, ultrasonic power and temperature are all critical parameters. Suggested wire is pure gold, 1 mil diameter. Bonds must be made from the bond pads on the die to the package or substrate. All bond wires should be kept as short as low as reasonable to minimize performance degradation due to undesirable series inductance.

